



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Sectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-05
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MABZ*VB15ACI	A	Z6RA	2016-09-05
Amount	UoM	Unit type	ST ECOPACK Grade	
0.46	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
Not Applicable	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC405)	Not Applicable	N/A		



Package Designator	Size	Nbr of instances	Shape	
BGA	1.8x1.8x0.221	4	No lead	
Comment	Package: AOSC CSPS0.35; MDF valid for LDLN025J2925R			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	MABZ*VB15ACI					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other Inorganic materials	0.250	mg	supplier	die	Silicon (Si)	7440-21-3		0.230	mg	920000	495690
				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	12000	6466
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	8000	4310
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	4000	2155
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	24000	12931
				supplier	bump	Copper (Cu)	7440-50-8		0.008	mg	32000	17241
Underfill	Other Organic Materials	0.070	mg	supplier	resin	silica vitreous	60676-86-0		0.034	mg	485714	73276
				supplier	resin	Epoxy resin	Proprietary		0.012	mg	171429	25862
				supplier	resin	Acrylic polymer	Proprietary		0.012	mg	171429	25862
				supplier	resin	Bis-phenol A diglycidyl ether	25036-25-3		0.004	mg	57143	8621
				supplier	resin	Iron compound	7439-89-6		0.004	mg	57143	8621
				supplier	resin	Zinc compound	7440-66-6		0.004	mg	57143	8621
connections coating	Solder	0.144	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.138	mg	955000	296997
				supplier	solder alloy	Copper (Cu)	7440-50-8		0.001	mg	5000	1555
				supplier	solder alloy	Silver (Ag)	7440-22-4		0.006	mg	40000	12440